

**Amendments to the Specification:**

Page 10, lines 4-18, replace the paragraph with the following:

A method of preparing an integrated circuit module for attachment to a ~~printed circuit~~ PC substrate. ~~At wherein~~ At ~~at least one uncased semiconductor die is affixed too to~~ wherein at least one uncased semiconductor die is affixed to a TAB tape frame ~~that has a~~ having concentrically arranged an outer conductive test pad footprint, ~~formed about the perimeter thereof and a bond pad footprint and an~~ intermediate bond pad footprint. ~~generally centrally disposed within the test pad footprint and where~~ conductive Conductive traces connect the bond pads individually to the test pads as well as and to ball grid array pads ~~that are generally centrally disposed on the~~ TAB tape within the confines of the bond pad footprint. Wire bonds ~~are then used to~~ connect input/output points of the semiconductor die to ~~selected ones of the bond pads in the bond pad footprint.~~ The semiconductor die and the wire bonding are next overmolded with a plastic ~~encapsulant to form~~ forming an a cased integrated circuit module. Testing and burn-in of the ~~integrated circuit~~ module is ~~then~~ achieved by connecting test probes to the ~~conductive test pads in the test pad footprint.~~ Only after After the test and burn-in step, ~~is completed~~ is the integrated circuit module is cut free from the TAB tape frame for attachment to a PC board, via the ball grid array and ~~mounted on a printed circuit board using reflow soldering of solder balls on the ball grid array to mating contact areas on the printed circuit board.~~